

-20V P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SMC3415A is the P-Channel logic enhancement mode power field effect transistor is produced using high cell density, advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM and gate charge for most of the synchronous buck converter applications.

SMC3415AS-TRG ROHS Compliant This is Halogen Free

FEATURE

- ◆ -20V/-4.0A, $R_{DS(ON)} = 43m\Omega(typ)@V_{GS} = -4.5V$
- ◆ -20V/-4.0A, $R_{DS(ON)} = 58m\Omega(typ)@V_{GS} = -2.5V$
- ◆ -20V/-2.0A, $R_{DS(ON)} = 78m\Omega(typ)@V_{GS} = -1.8V$
- ◆ -20V/-1.0A, $R_{DS(ON)} = 98m\Omega(typ)@V_{GS} = -1.5V$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability

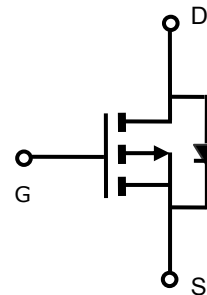
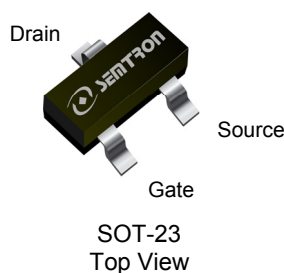
APPLICATIONS

- ◆ Cellular/Portable
- ◆ Load Switch



P-Channel Enhancement Mode MOSFET

PIN CONFIGURATION



PART NUMBER INFORMATION

<p>SMC 3415A S - TR G</p> <p>a b c d e</p>	<p>a : Company name. b : Product Serial number. c : Package code d : Handling code e : Green produce code</p>
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ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
SMC3415AS-TRG	S : SOT-23	TR : Tape&Reel	3K/Reel

- ※ Year Code : 0 ~ 9, 2010 : 0
- ※ Week Code : A(1~2) ~ Z(53~54)
- ※ SOT-23 : Only available in tape and reel packaging.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical	Unit	
V_{DSS}	Drain-Source Voltage	-20	V	
V_{GSS}	Gate-Source Voltage	± 10	V	
I_D	Continuous Drain Current ($T_C=25^\circ\text{C}$) ^A	$V_{GS}=4.5\text{V}$	-4.7	A
	Continuous Drain Current ($T_C=100^\circ\text{C}$)		-3.0	A
I_{DM}	Pulsed Drain Current ^B	-18.8	A	
P_D	Power Dissipation	$T_A=25^\circ\text{C}$	1.56	W
		$T_A=70^\circ\text{C}$	1.02	
T_J	Operation Junction Temperature	-55 to 150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged.
- Absolute maximum ratings are stress ratings only and functional device operation is not implied.

THERMAL DATA

Symbol	Parameter	Typ	Max	Unit	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ^A	Steady-State	-	140	$^\circ\text{C/W}$
$R_{\theta JL}$	Thermal Resistance Junction to Lead ^A	Steady-State	-	80	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.4	-0.6	-0.8	V
I_{GSS}	Gate Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -24V, V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			-10	
$R_{DS(ON)}$	Drain-source On-Resistance ^B	$V_{GS} = -4.5V, I_D = -4.0A$		43	50	m Ω
		$V_{GS} = -2.5V, I_D = -4.0A$		58	65	
		$V_{GS} = -1.8V, I_D = -2.0A$		78	85	
		$V_{GS} = -1.5V, I_D = -1.0A$		98	106	
G_{fs}	Forward Transconductance	$V_{DS} = -10V, I_S = -3.0A$		7		S
Source-Drain Diode						
V_{SD}	Diode Forward Voltage	$I_S = -1A, V_{GS} = 0V, T_J = 25^\circ\text{C}$		-0.8	-1.0	V
I_S	Continuous Source Current ^{AC}				-4.7	A
Dynamic Parameters						
Q_g	Total Gate Charge	$V_{DS} = -10V, V_{GS} = -4.5V,$ $I_D = -3.0A$		9.6	14	nC
Q_{gs}	Gate-Source Charge			1.65	2	
Q_{gd}	Gate-Drain Charge			2.1	3.9	
C_{iss}	Input Capacitance	$V_{DS} = -10V, V_{GS} = 0V,$ $f = 1\text{MHz}$		848	1228	pF
C_{oss}	Output Capacitance			771	103	
C_{rss}	Reverse Transfer Capacitance			57	82	
$t_{d(on)}$	Turn-On Time	$V_{DD} = 15V, V_{GS} = -10V,$ $I_D = -1A, R_G = 25\Omega$		10		nS
T_r				9.7		
$t_{d(off)}$	Turn-Off Time			85		
t_f				9.7		

Note:

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_C = 25^\circ\text{C}$.

B. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

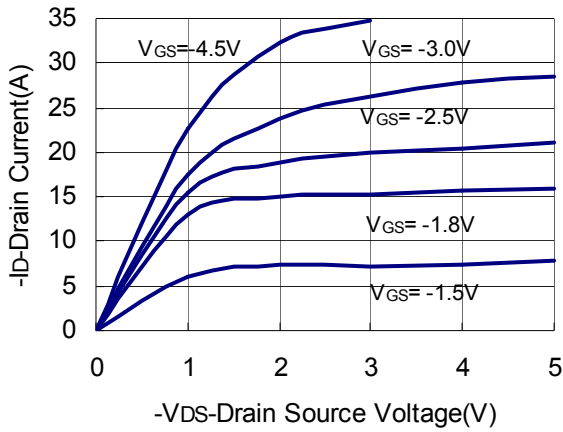
C. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

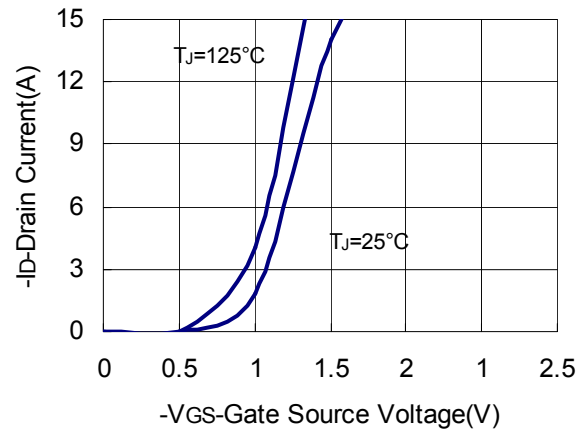
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TYPICAL CHARACTERISTICS (25°C Unless Note)

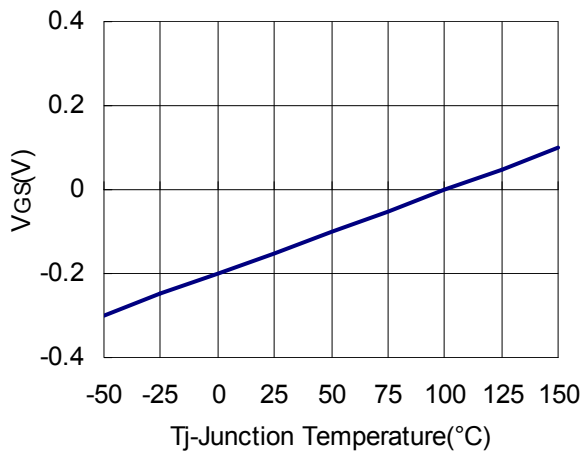
Output Characteristics



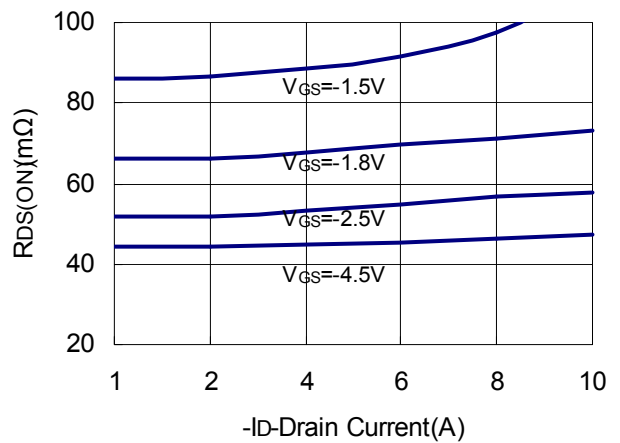
Transfer Characteristics



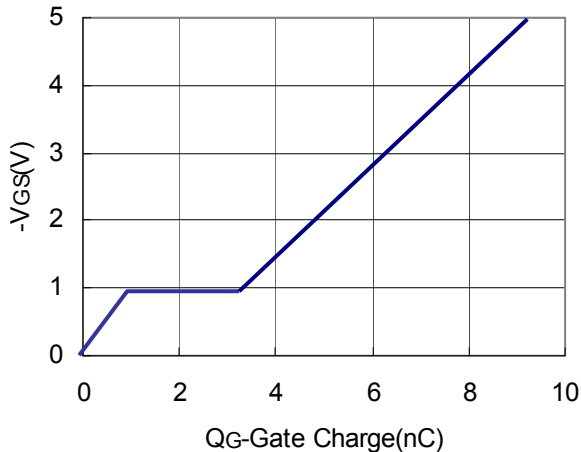
Gate Threshold Voltage



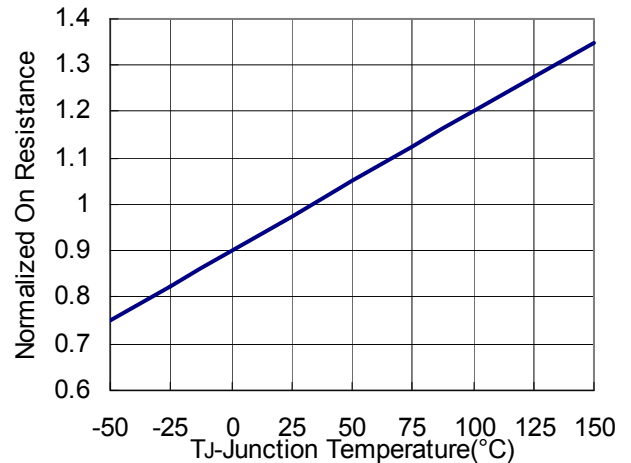
Drain Source On Resistance



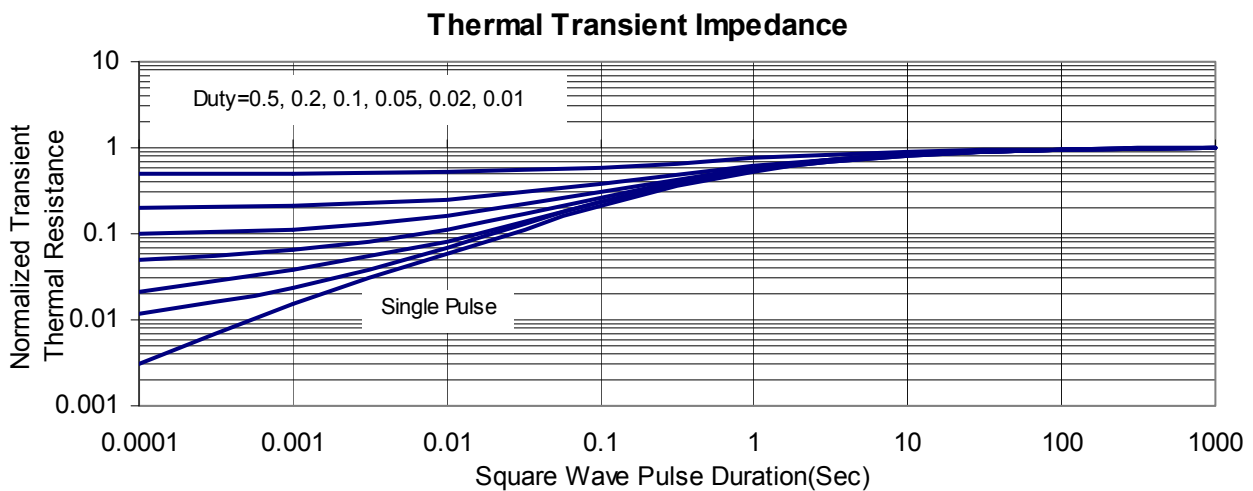
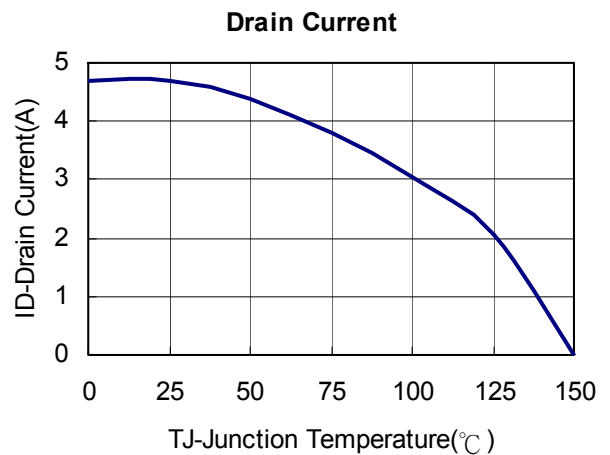
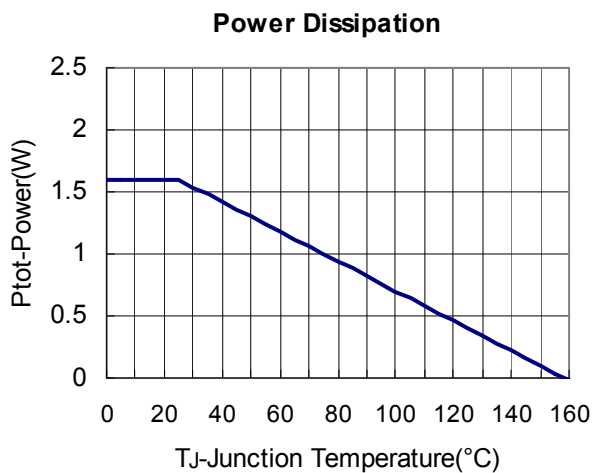
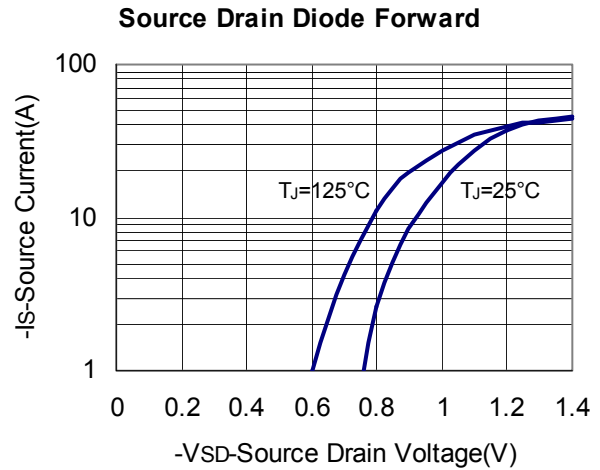
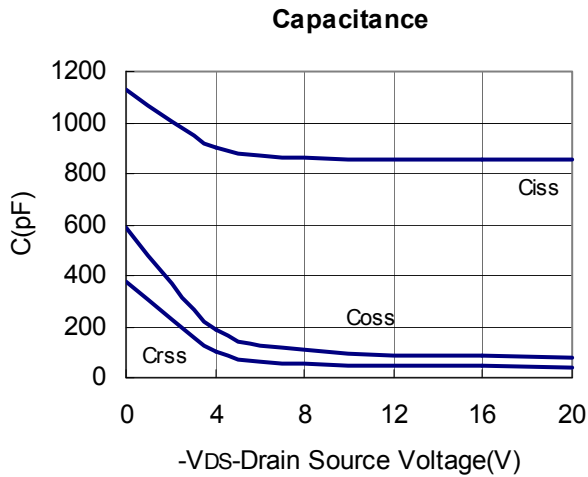
Gate Charge



Drain Source On Resistance



TYPICAL CHARACTERISTICS (25°C Unless Note)



■ SOT-23 PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L1	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

